ABSTRACT

The present invention is a novel method and apparatus for burn-in testing an electronic device. A device under test (DUT) is attached to a burn-in board (BIB), a thermally conductive sheet is placed atop the DUT, the BIB is placed in an environmentally-controlled burn-in oven, and current is applied to the DUT. A test signal can be sent to the DUT and data received from the DUT to determine whether the DUT is working properly. Aluminum, copper, or any material as thermally conductive as aluminum may be used in the sheet. The sheet may have top or bottom surface areas that conduct more heat away from the device and into the ambient environment than that conducted by a flat sheet. The sheet may be applied to a plurality of DUTs simultaneously. Further, a second thermally conductive sheet may be located underneath the BIB and in thermal contact with it.